



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

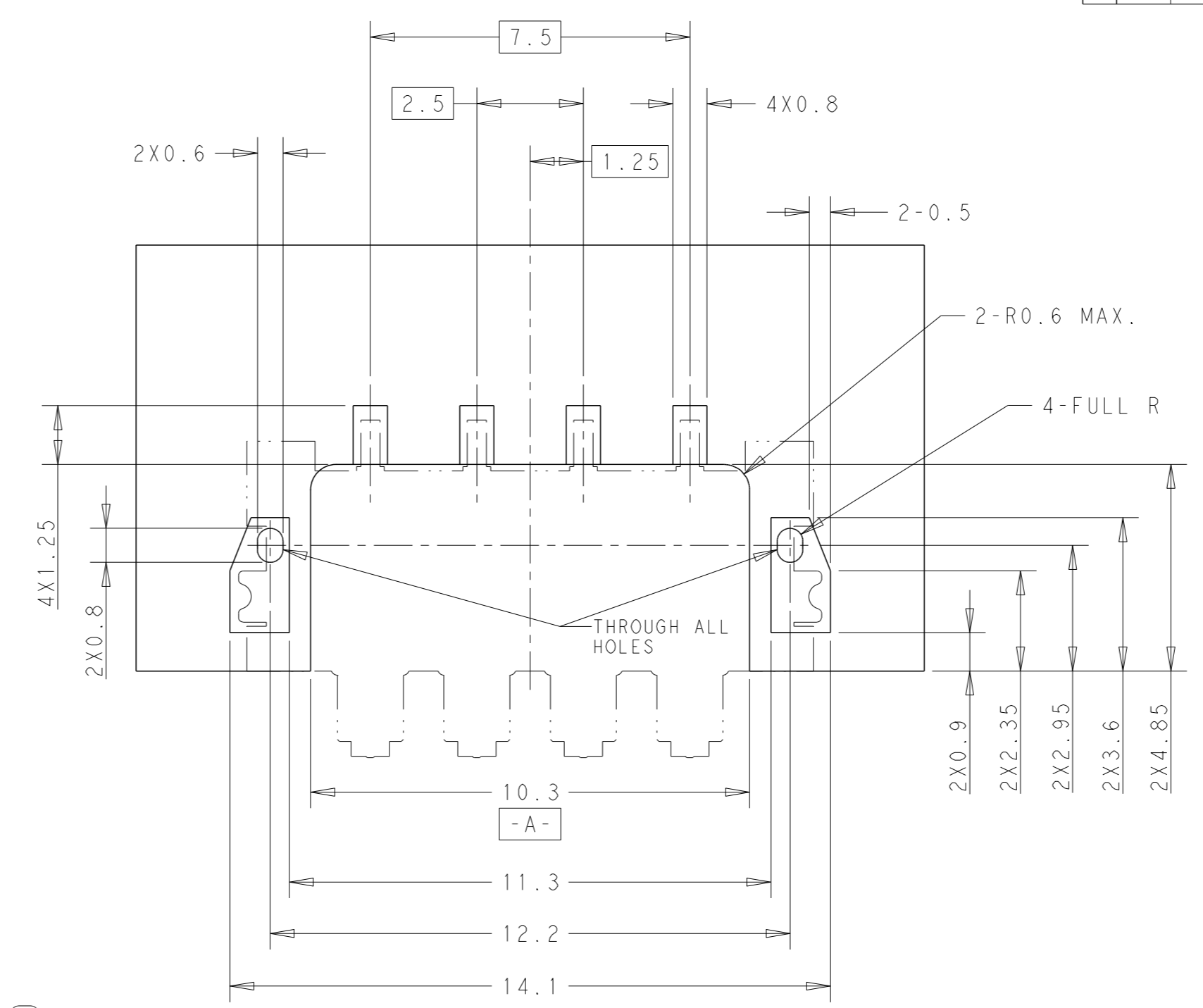
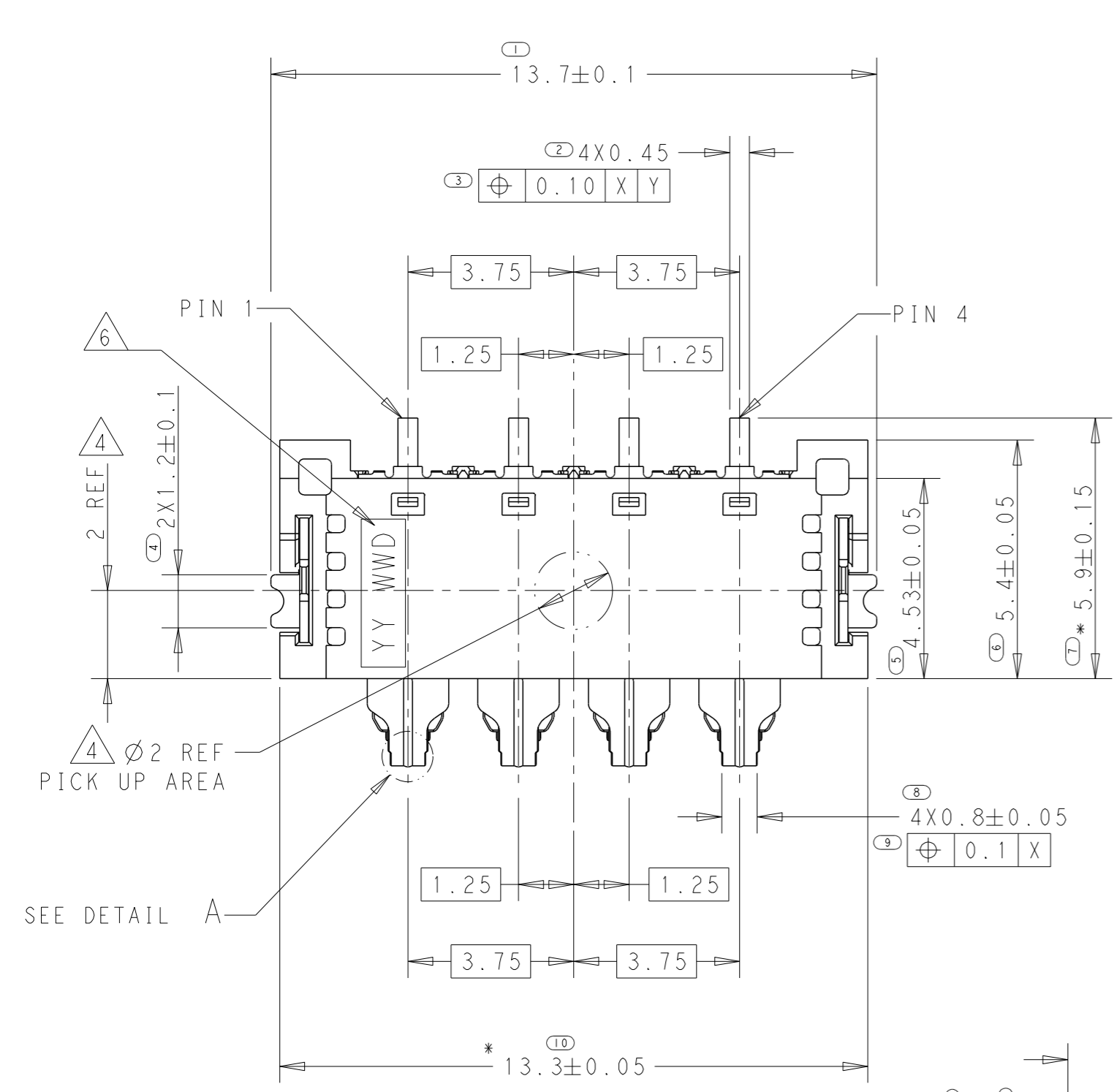
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

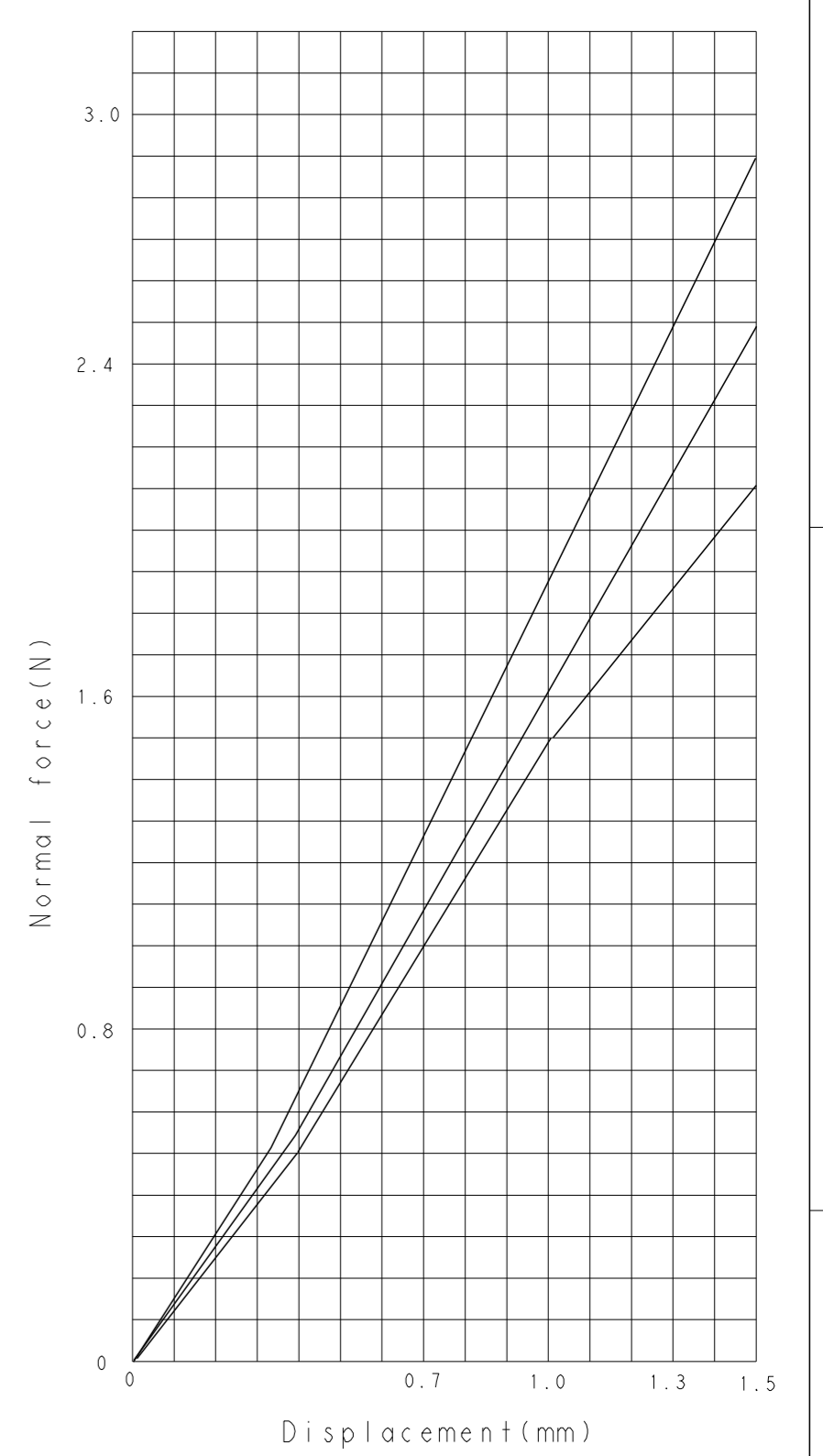
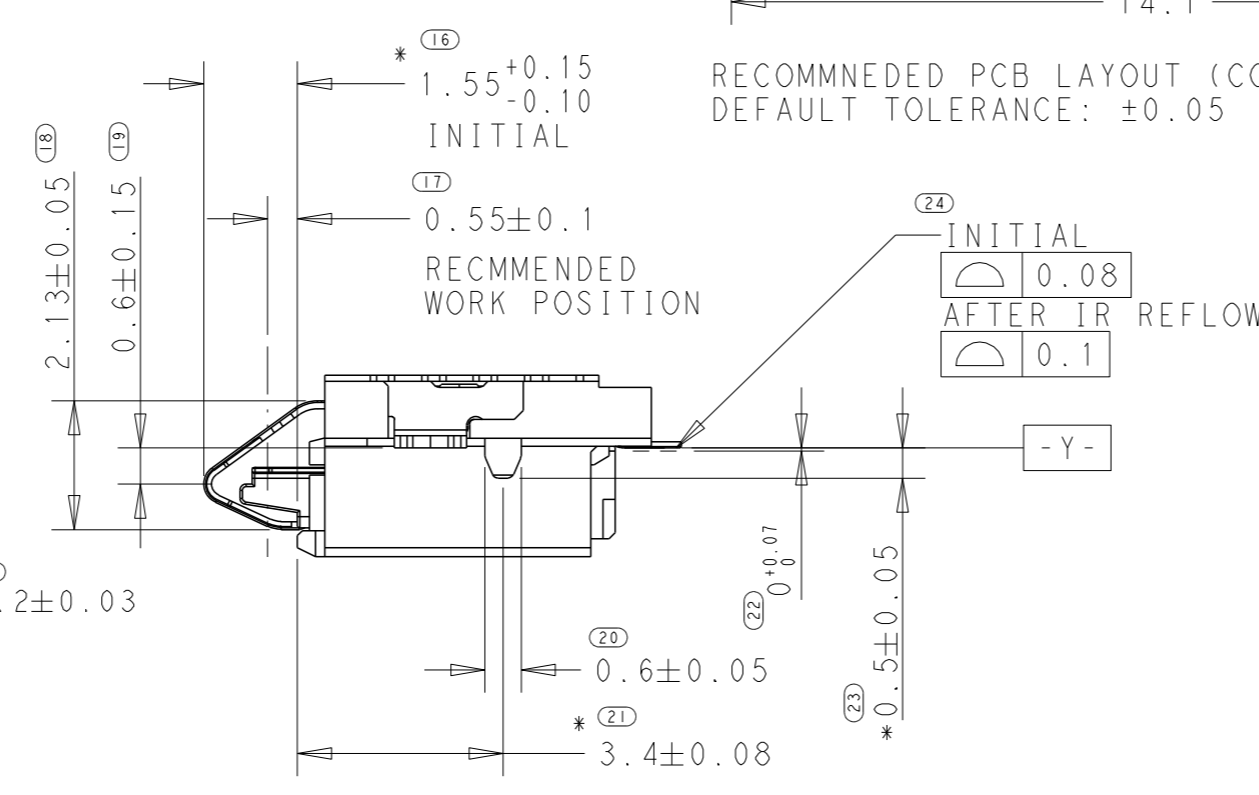
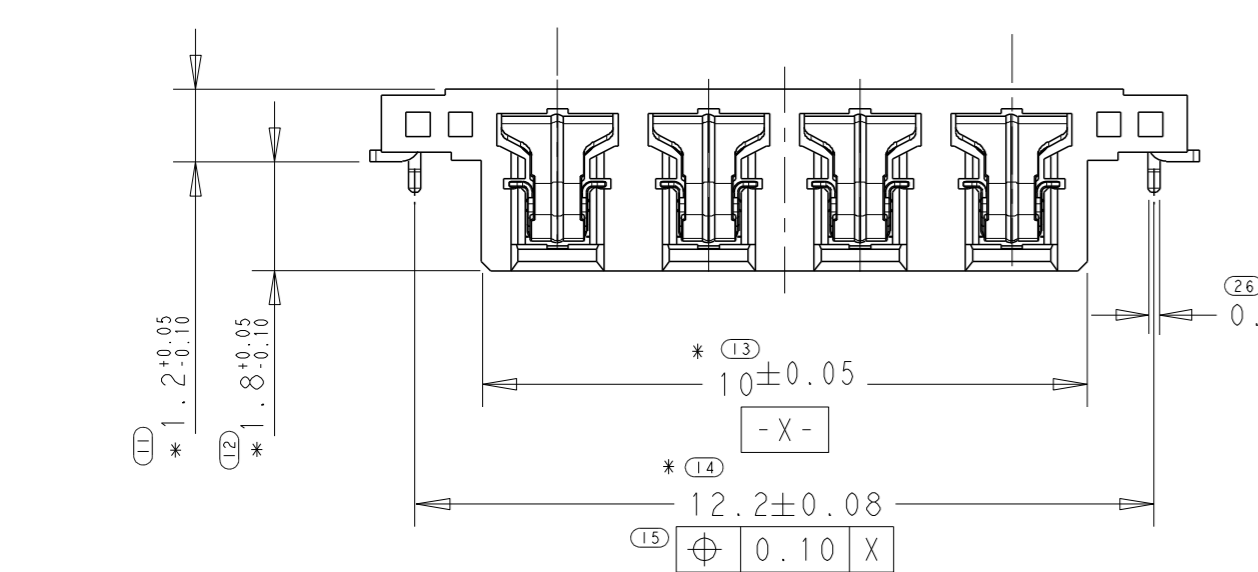
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REVISIONS				
P	LTR	DESCRIPTION	DATE	DWN APVD
	A2	REVISED	21SEP2015	J. J. W. H.

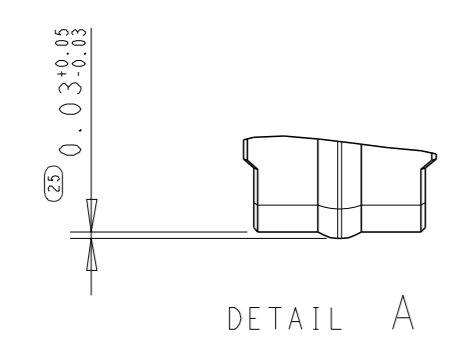


RECOMMENDED PCB LAYOUT (COMPONENTS SIDE VIEW)
 DEFAULT TOLERANCE: ±0.05

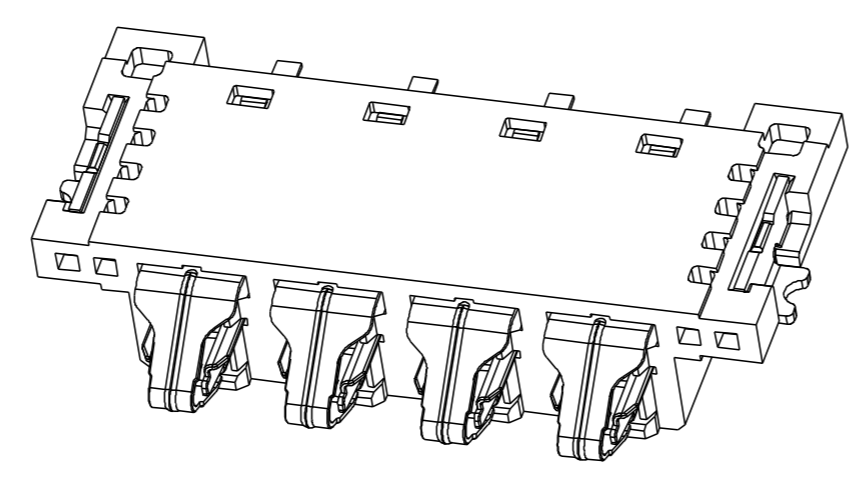


NORMAL FORCE CURVE FOR REFERENCE

- 1 MATERIAL
 CONTACT: NICKEL COPPER.
 HOUSING: LCP, UL94V-0, BLACK.
 SOLDER PEG: BRASS OR STAINLESS STEEL.
- 2 FINISH
 CONTACT: 1.25µm MIN. NICKEL UNDER PLATING
 0.375µm MIN. GOLD PLATING AT CONTACT AREA.
 0.025µm MIN. GOLD PLATING AT SOLDERING AREA
 SOLDER PEG: 1.0µm MIN. NICKEL UNDER PLATING
 1.5µm MIN. TIN PLATING
- 3 COPLANARITY 0.08 MAX.
- 4 PICK UP AREA
- 5 EMBOSS AND COVER TAPE: ESD PROTECTION MATERIAL
- 6 MARK WITH DATE CODE, YYWWD: YY-YEAR, WW-WEEK, D-DAY
- 7 STORAGE LIFE: AT LEAST 12 MONTHS
- 8 PART NO : 2289817-1

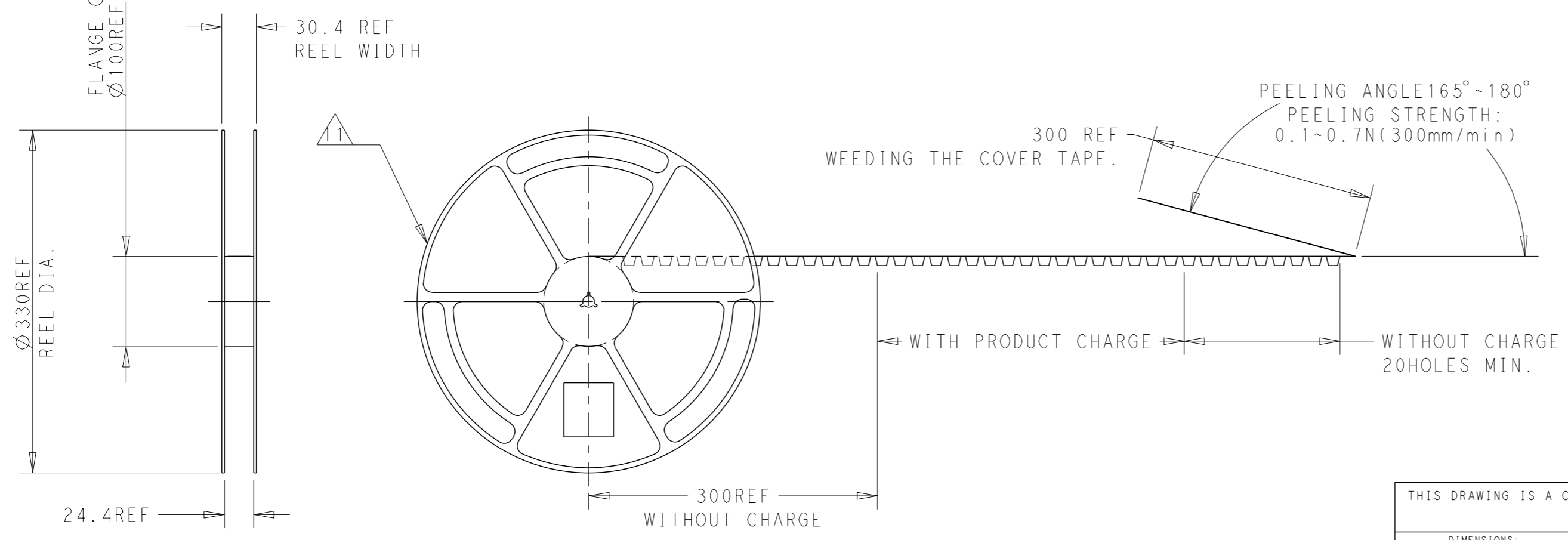
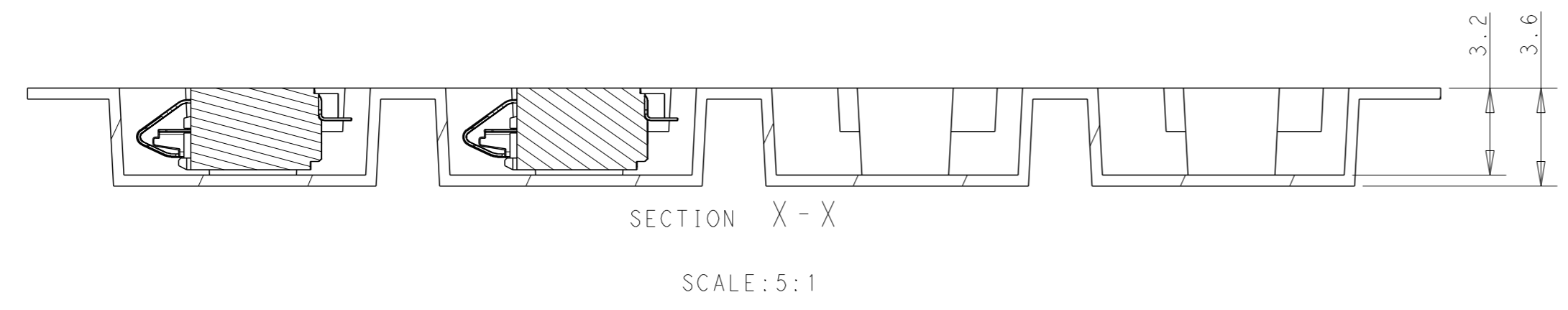
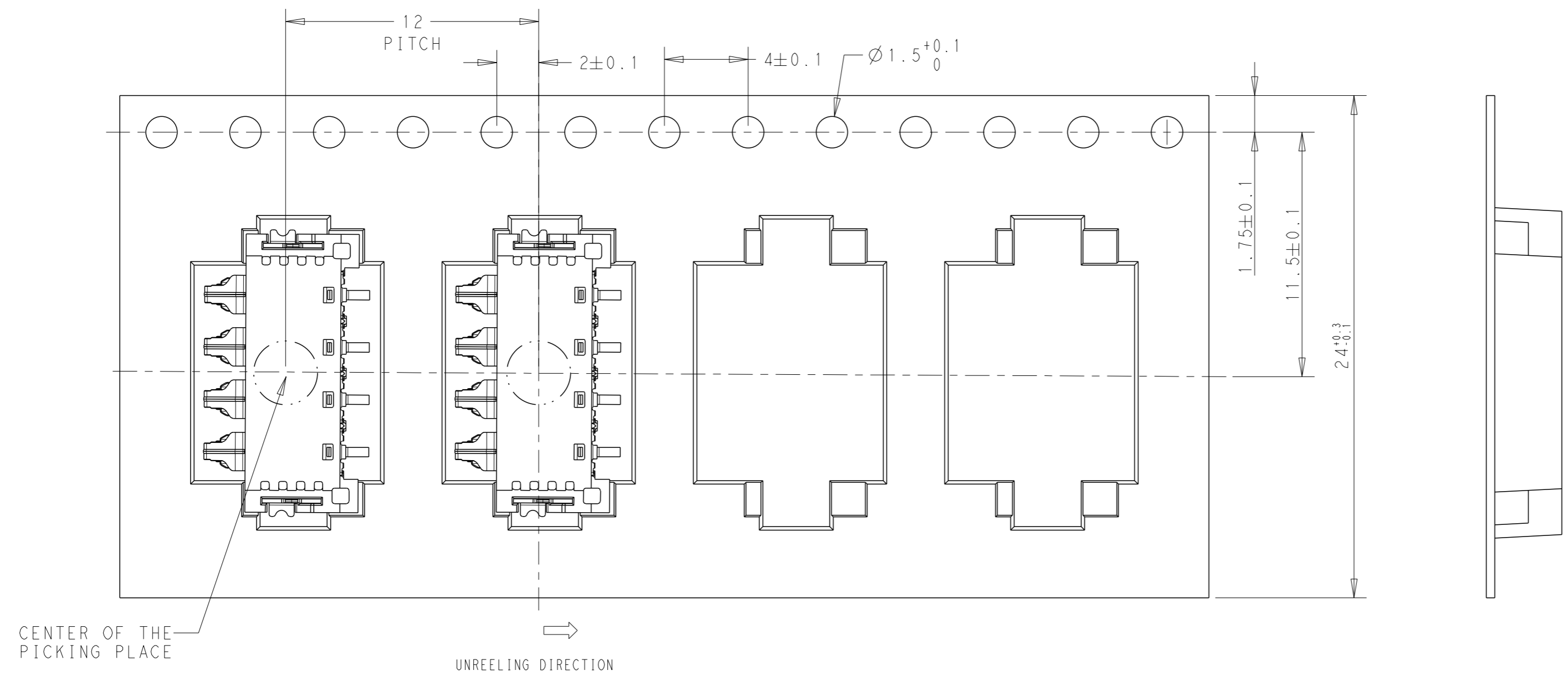


DETAIL A



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. YASUI 25FEB2015	TE Connectivity		
DIMENSIONS: mm		CHK A. KUBO 25FEB2015			
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD T. MATSUDAIRA 25FEB2015	NAME LOW PROFILE BATTERY		
0 PLC ± 1 PLC ±0.35 2 PLC ±0.25 3 PLC ±0.05 4 PLC ±0.02 ANGLES ± FINISH 1 2		PRODUCT SPEC -	SIZE A2	RESTRICTED TO -	
MATERIAL 1		APPLICATION SPEC -	CAGE CODE -	DRAWING NO. C=2289817	
		WEIGHT -	SCALE NTS	SHEET 1 OF 2	
		CUSTOMER DRAWING	REV A2		

REVISIONS				
P	LTR	DESCRIPTION	DATE	APVD



1500	2289817-1
QTY/REEL	P/N

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN HILL HE 10FEB2015	TE Connectivity	
DIMENSIONS: mm		CHK WENKE HE 10FEB2015		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD WENKE HE 10FEB2015	NAME LOW PROFILE BATTERY	
		PRODUCT SPEC	SIZE A2	
MATERIAL TBD		APPLICATION SPEC	CAGE CODE -	DRAWING NO C=2289817
WEIGHT -		RESTRICTED TO -	SCALE 10:1	SHEET 2 OF 2
CUSTOMER DRAWING		REV A2		